

ABSTRACT

There is provided a resist composition used for the production of printed boards, which comprises (A) a resin component, (B) a photopolymerization initiator, (C) water and (D) an organic solvent, wherein the organic solvent (D) contains:

(D-1) at least one organic solvent selected from the group consisting of an α -hydroxycarboxylate ester, a β -alkoxycarboxylate ester, a 1,3-diol compound and a 1,3-diol compound derivative, and

(D-2) an organic solvent having a hydroxyl group other than (D-1).